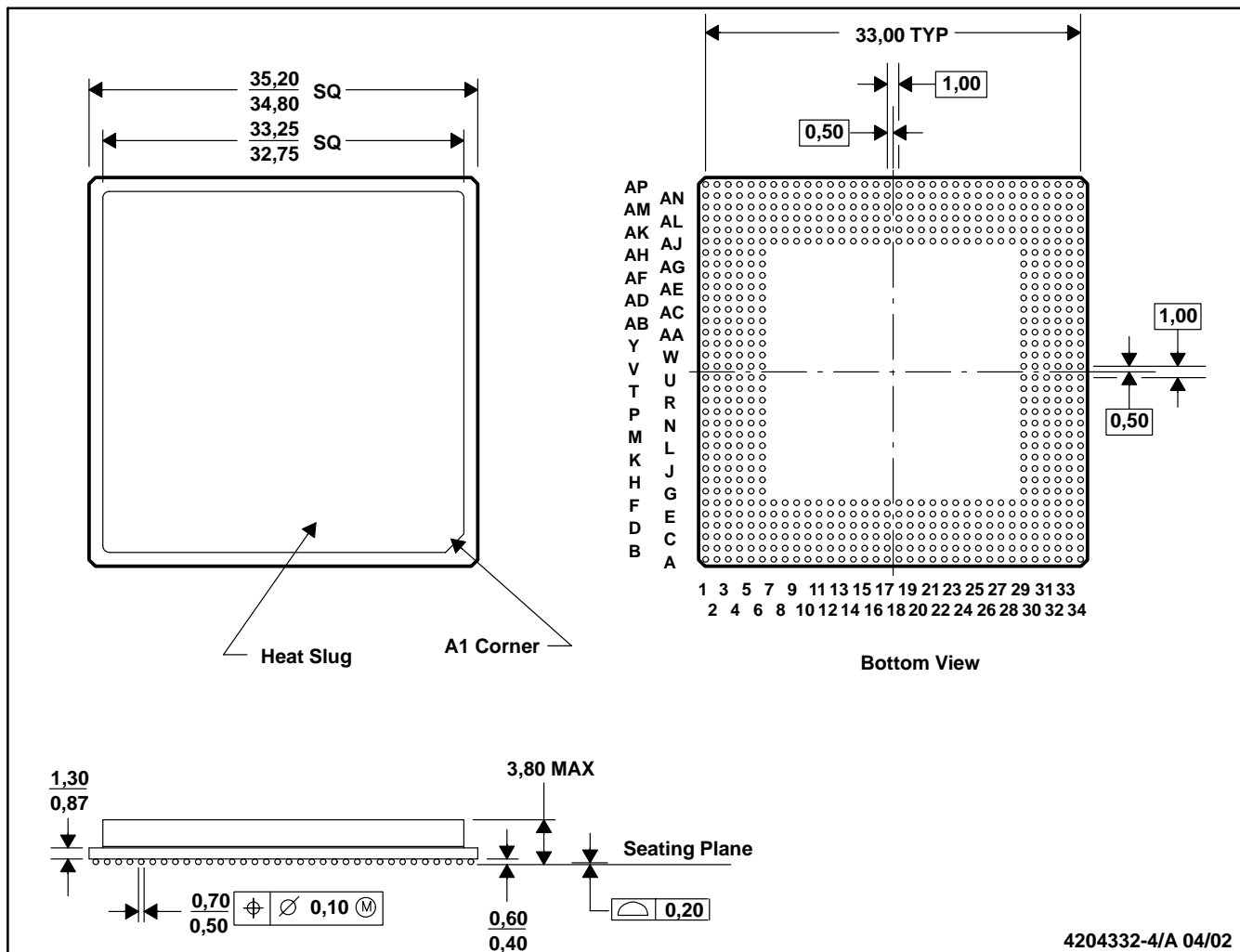


GDN (S-PBGA-N672)

PLASTIC BALL GRID ARRAY



4204332-4/A 04/02

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Flip chip application only.

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